

### **60V N-Channel Enhancement Mode MOSFET**

Voltage 60 V Current 95 A

#### **Features**

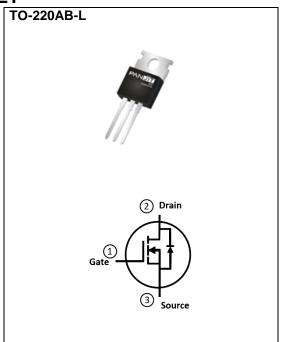
- RDS(ON), VGS@10V, ID@20A<6.1m $\Omega$
- RDS(ON), VGS@4.5V, ID@10A<10m $\Omega$
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

#### **Mechanical Data**

• Case: TO-220AB-L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 2.0948 grams



# **Maximum Ratings and Thermal Characteristics** (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		$V_{DS}$	60	V	
Gate-Source Voltage		$V_{GS}$	±20	v	
Continuous Drain Current(Note 3)	T <sub>C</sub> =25°C		95		
	Tc=100°C	l <sub>D</sub>	68	Α	
Pulsed Drain Current(Note 1)	T <sub>C</sub> =25°C	I <sub>DM</sub>	345		
Power Dissipation	T <sub>C</sub> =25°C	D-	100	W	
	Tc=100°C	Po	50		
Continuous Drain Current(Note 4)	T <sub>A</sub> =25°C		15	А	
	T <sub>A</sub> =70°C	I <sub>D</sub>	12.4		
Power Dissipation	T <sub>A</sub> =25°C	PD	2.4	W	
	T <sub>A</sub> =70°C		1.7		
Single Pulse Avalanche Current(Note 5)		I <sub>AS</sub>	27	А	
Single Pulse Avalanche Energy <sup>(Note 5)</sup>		E <sub>AS</sub>	69	mJ	
Operating Junction and Storage Temperature Range		T <sub>J</sub> ,T <sub>STG</sub>	-55~175	°C	
Thermal Resistance <sup>(Note 4)</sup>	Junction to Case	R <sub>θ</sub> JC	1.5	°C/W	
	Junction to Ambient	R <sub>θJA</sub>	62.5		



### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	-	-	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.5	2.1	3	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	4.9	6.1	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	-	7.7	10	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	ı	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	ı	-	±100	nA
Dynamic <sup>(Note 6)</sup>						
Total Gate Charge	Qg	V <sub>DS</sub> =30V, I <sub>D</sub> =20A,	ı	40	52	nC
Gate-Source Charge	Qgs		-	9.6	-	
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V	-	8.3	-	
Input Capacitance	Ciss	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V,	-	2039	2650	pF
Output Capacitance	Coss		-	695	973	
Reverse Transfer Capacitance	Crss	f=1MHz	-	91	-	
Gate resistance	Rg	f=1MHz	-	0.88	-	Ω
Turn-On Delay Time	td <sub>(on)</sub>	$V_{DS}$ =30V, $I_{D}$ =20A, $V_{GS}$ =10V, $R_{G}$ =3 $\Omega$ (Note 2)	-	9	-	
Turn-On Rise Time	tr		-	35	-	
Turn-Off Delay Time	td <sub>(off)</sub>		ı	29	-	ns
Turn-Off Fall Time	tf	(14016-2)	-	59	-	
Drain-Source Diode						
Diode Forward Current	Is	T 05°0	-	-	95	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> =25°C	-	-	345	A
Diode Forward Voltage	V <sub>SD</sub>	Is=20A, V <sub>GS</sub> =0V	-	0.85	1.3	V
Reverse Recovery Time	Trr	V <sub>DD</sub> =30V,V <sub>GS</sub> =0V	-	37	-	ns
Reverse Recovery Charge	Qrr	Is=20A,dIs/dt=100A/us	-	18	-	nC

#### NOTES:

- 1. Pulse width<a></a>100us, Duty cycle<a></a>2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R<sub>eJC</sub>=1.5°C/W.
- 4.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance.
- 5. E<sub>AS</sub> is calculated based on the condition of L=1mH, I<sub>AS</sub>=12A, V<sub>DD</sub>=30V, V<sub>GS</sub>=10V. 100% test at L=0.1mH, I<sub>AS</sub>=27A in production.
- 6. Guaranteed by design, not subject to production testing.



#### **TYPICAL CHARACTERISTIC CURVES**

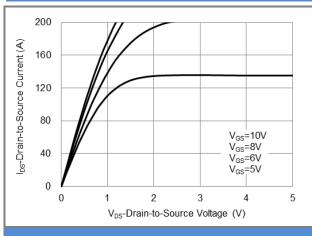


Fig.1 On-Region Characteristics

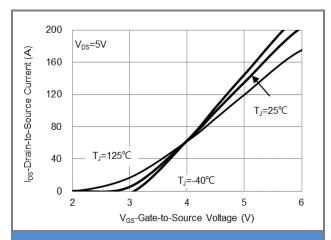


Fig.2 Transfer Characteristics

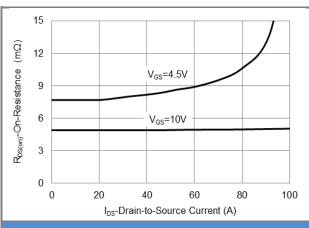


Fig.3 On-Resistance vs. Drain Current

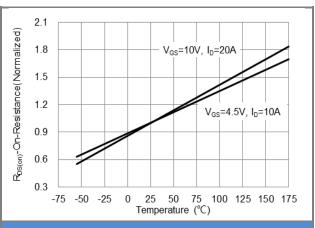
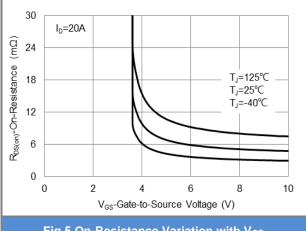
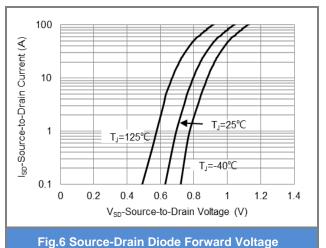


Fig.4 On-Resistance vs. Junction temperature









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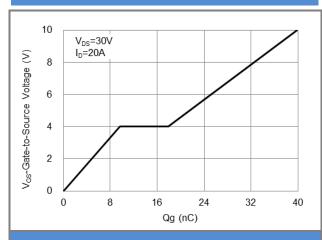


Fig.7 Gate-Charge Characteristics

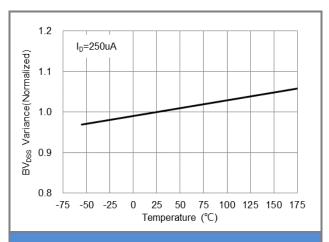


Fig.8 Breakdown Voltage Variation vs. Temperature

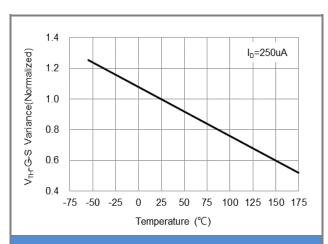


Fig.9 Threshold Voltage Variation with Temperature

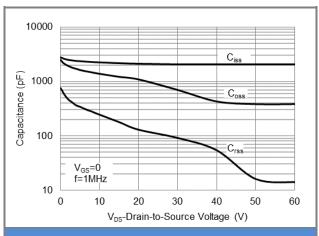
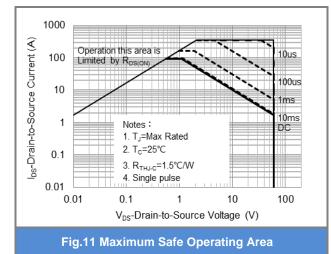
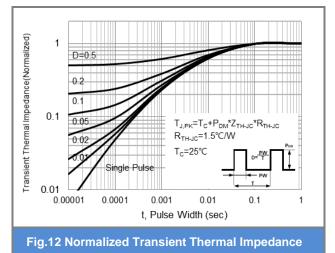


Fig.10 Capacitance vs. Drain-Source Voltage



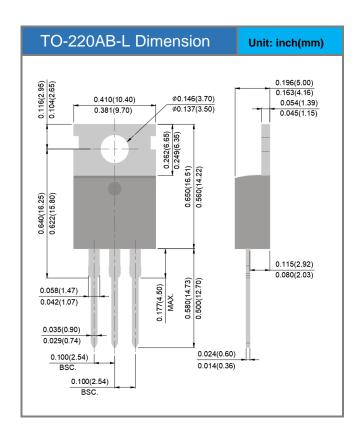




### **Product and Packing Information**

Part No.	Package Type	Packing Type	Marking
PJP100N06SA-AU	TO-220AB-L	50 pcs / Tube	100N06SA

### **Packaging Information**





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